



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SPECIFICATION

(Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

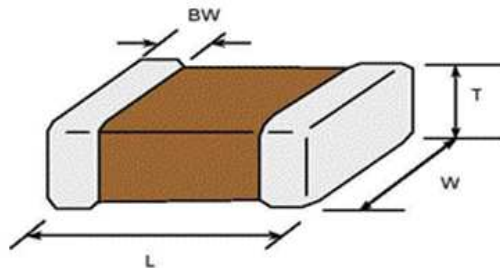
- Samsung P/N : **CL21C470JBANNNC**
- Description : **CAP, 47pF, 50V, ± 5%, COG, 0805**

A. Samsung Part Number

CL **21** **C** **470** **J** **B** **A** **N** **N** **N** **C**
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| | | | | |
|--------------------------------|---------------------------------------|--------------------------|-------------------------|--|
| ① Series | Samsung Multi-layer Ceramic Capacitor | | | |
| ② Size | 0805 (inch code) | L: 2.00 ± 0.10 mm | W: 1.25 ± 0.10 mm | |
| ③ Dielectric | COG | ⑧ Inner electrode | Ni | |
| ④ Capacitance | 47 pF | Termination | Cu | |
| ⑤ Capacitance tolerance | ± 5% | Plating | Sn 100% (Pb Free) | |
| ⑥ Rated Voltage | 50 V | ⑨ Product | Normal | |
| ⑦ Thickness | 0.65 ± 0.10 mm | ⑩ Special | Reserved for future use | |
| | | ⑪ Packaging | Cardboard Type, 7" reel | |

B. Structure and dimension



| Samsung P/N (Lead Free) | Dimension(mm) | | | |
|----------------------------|---------------|-------------|-------------|-----------------|
| | L | W | T | BW |
| CL21C470JBANNNC | 2.00 ± 0.10 | 1.25 ± 0.10 | 0.65 ± 0.10 | 0.50+0.20/-0.30 |

C. Samsung Reliability Test and Judgement condition

| | Performance | Test condition |
|----------------------------------|--|---|
| Capacitance | Within specified tolerance | 1MHz±10% / 0.5~5Vrms |
| Q | 1,000 min | |
| Insulation Resistance | 10,000Mohm or 500Mohm× μ F Whichever is smaller | Rated Voltage 60~120 sec. |
| Appearance | No abnormal exterior appearance | Microscop (X10) |
| Withstanding Voltage | No dielectric breakdown or mechanical breakdown | 300% of the rated voltage |
| Temperature Characteristics | COG (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃) | |
| Adhesive Strength of Termination | No peeling shall be occur on the terminal electrode | 500g×F, for 10±1 sec. |
| Bending Strength | Capacitance change : within ±5% or ±0.5pF whichever is larger | Bending to the limit (1mm) with 1.0mm/sec. |
| Solderability | More than 75% of terminal surface is to be soldered newly | SnAg3.0Cu0.5 solder 245±5℃, 3±0.3sec. (preheating : 80~120℃ for 10~30sec.) |
| Resistance to Soldering heat | Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ , IR : initial spec. | Solder pot : 270±5℃, 10±1sec. |
| Vibration Test | Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ , IR : initial spec. | Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours ´ 3 direction (x, y, z) |
| Moisture Resistance | Capacitance change : within ±7.5% or ±0.75pF whichever is larger Q : 200 min IR : 500Mohm or 25Mohm × μ F Whichever is smaller | With rated voltage 40±2℃, 90~95%RH, 500+12/-0hrs |
| High Temperature Resistance | Capacitance change : within ±3% or ±0.3pF whichever is larger Q : 350 min IR : 1,000Mohm or 50Mohm × μ F Whichever is smaller | With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs |
| Temperature Cycling | Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ , IR : initial spec. | 1 cycle condition Min. operating temperature → 25℃ → Max. operating temperature → 25℃ 5 cycle test |

※ The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5℃, 10sec. Max)



Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

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The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

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We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

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- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- ③ Medical equipment
- ④ Military equipment
- ⑤ Disaster prevention/crime prevention equipment
- ⑥ Any other applications with the same as or similar complexity or reliability to the applications set forth above.